

Plasma Processing System
VITA Series

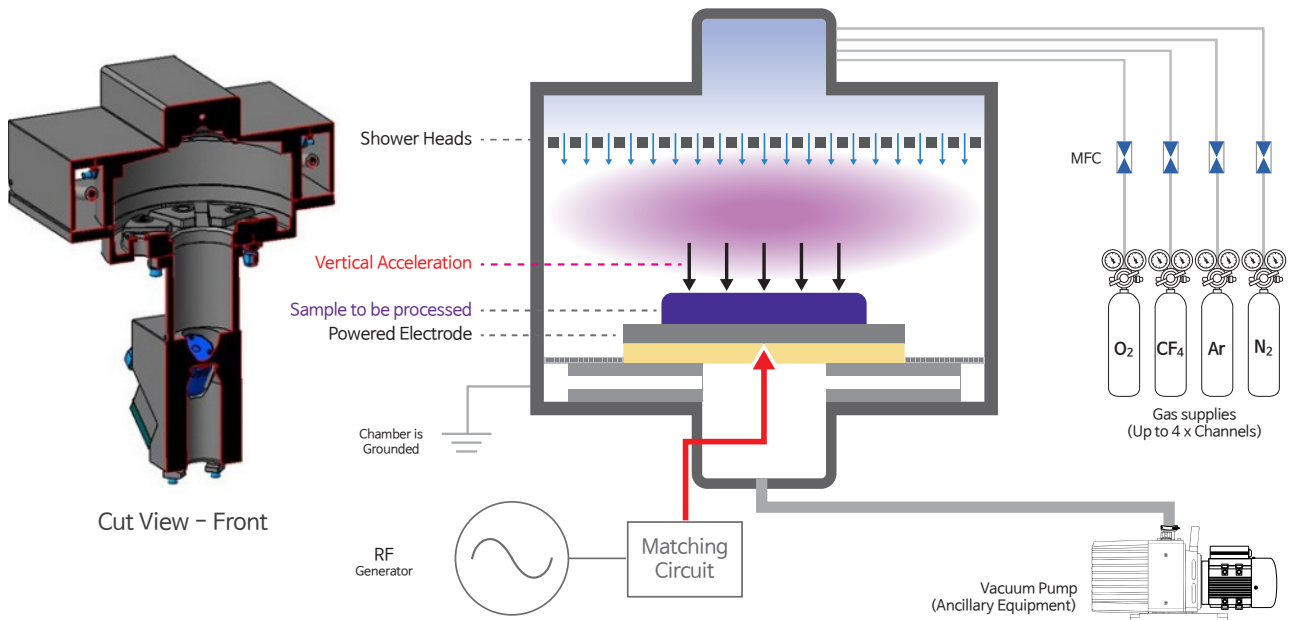


Specification



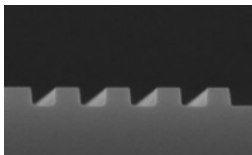
Model	VITA-8	VITA-12
Process Mode	RIE MODE	
MFC	Max. 200 sccm	
Pressure	Atm ~ 5×10^{-4} Torr	
Operation	Manual & Automatic	
Electrode Size	9.2 inch (Loading up to 8" round substrate)	14.4 inch (Loading up to 12" round substrate)
RF Generator	13.56MHz Up to 300W (Opt. 600W)	13.56MHz Up to 600W (Opt. 1,000W)
Geometry	W.680 x D.1,030 x H.1,200 (mm)	W.748 x D.1,139 x H.1,220 (mm)

Vertical Chamber Design



Applications

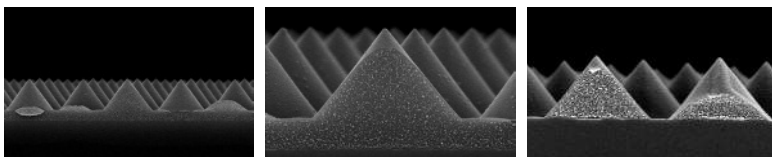
Semiconductor



Process Recipe

- CF_4 : 5 sccm, CHF_3 : 25 sccm , Ar : 70 sccm
- Pressure : 130 mTorr
- RF Power : 600W
- Chuck Temp. : 20°C
- ~ 2000Å/min
- Selectivity (PR : SiO_2) = 1:3

Removal of OLED Imprinting Residue



Removal Rate

- 70~100 nm/min (Typical)
- 30~40 nm/min (Soft)

※ 경기도 지역협력연구센터(GRRC) 사업비를 지원받아 제작



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